ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both This	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information				
Supplier Inforn	nation														
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
onsemi											2025-06-09				
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-Stew	ards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Repres	entative*		Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stew	ards	Product Enviro Compliance			I	NA				Product-Env-Stewards@onsemi.com					
Request	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	ve Date		Manufacturing Site	,	Weight*	UOM	Unit Type	
		NCP133AMX105TCG 500mA VLDO I option, Vout=1.0		500mA VLDO Bia option, Vout=1.05	as Rail CMOS Vreg V	g, AD	2025-06-09 MY1		MY1		1.855	mg	Each		
Ianufacturing	Proccess Informatio	n													
Terminal Plating / Grid Array Material T			Germinal Base Alloy J-STD-020 MSL		-STD-020 MSL Ra	ting	Peak Process Body Temperature Max Time at Pea			re Max Time at Peak	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed			CU Alloy 1				260	260 C 30		30	seconds 3				
omments															
vel 1 - maximum	ime at peak temperature	during sold	dering is 10-3	0 seconds								·			
or more informati	on regarding material co	mposition p	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Die Attach Epoxy	0.03	mg		Epoxy resin	proprietary data		0.003	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0001	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0014	mg
			Supplier	Silver (Ag)	7440-22-4		0.0255	mg
Lead Frame	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0328	mg
			Supplier	Tin (Sn)	7440-31-5		0.0021	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0018	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0021	mg
			Supplier	Copper (Cu)	7440-50-8		0.7813	mg
Mold Compound-Black	0.88	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0704	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0044	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0176	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.7612	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0264	mg
Plating	0.02	mg	Supplier	Tin (Sn)	7440-31-5		0.02	mg
Wire Bond	0.015	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0147	mg